

Descrizione del prodotto

La pasta BEST-solder (Tin) è la migliore scelta di IC reballing.

marchio BEST originale,

Qualità verificata

Applicazione: può essere utilizzato per laptop / computer / telefono cellulare / elettrodomestici SMD IC e riparazione BGA IC, strumenti per chip a livello di chipriparazione e linea di produzione elettronica.

Parametro tecnologico

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SOLDER PASTE

Lead-free High temperature



500g

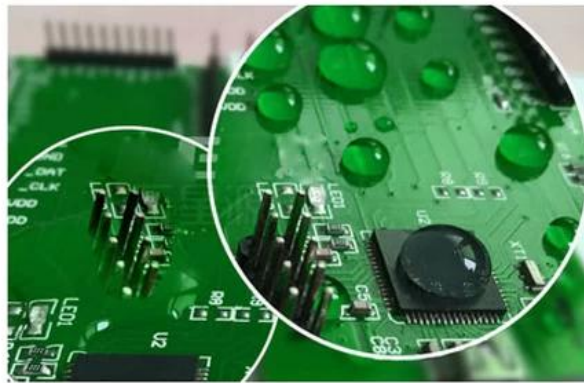
Low residue / Rapid welding / lead free / Solder spot bright / Ag

Product Usage

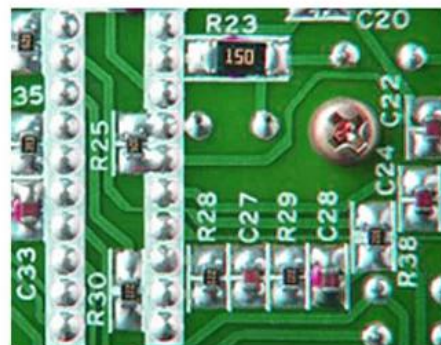
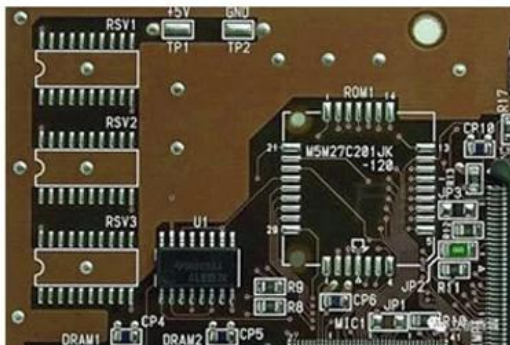


MODEL	BST-705
SHELF LIFE	6 months
INGREDIENT	Sn99/Ag0.3/Cu0.7
WEIGHT	500g
MELTING POINT	217°C

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue

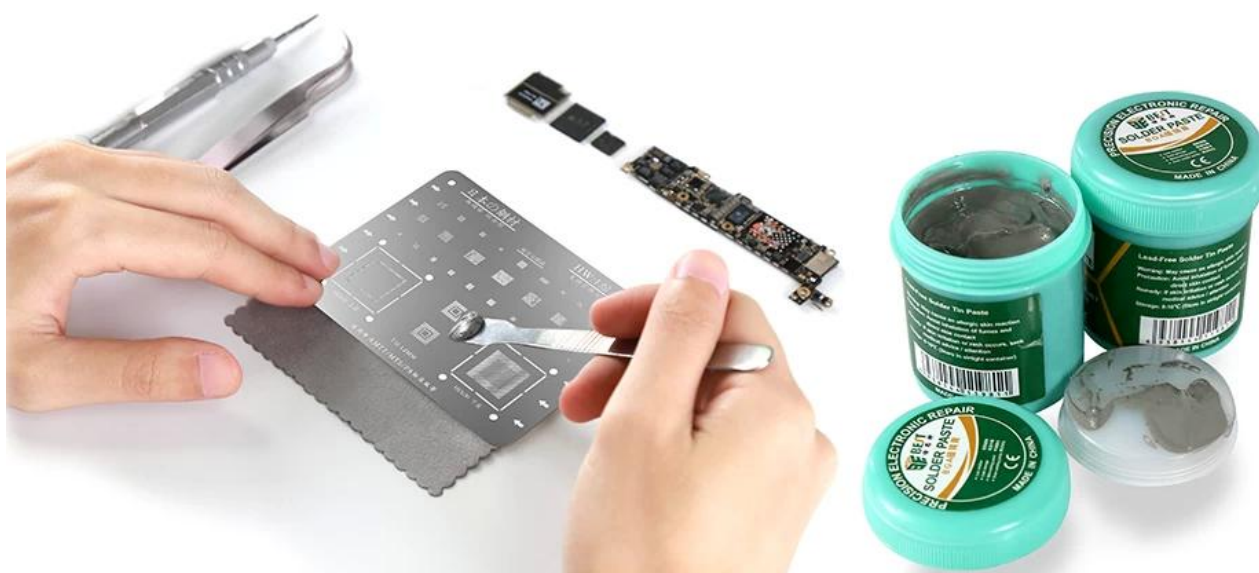


Welding requirements for a wide range of products



TESTING EFFECT

UNIFORM SOLDER JOINT
MEDIUM TEMPERATURE MELTING POINT



PRODUCT SIZE



63.0MM



52MM

75MM

